



DST3904DJ

#### **40V DUAL NPN SURFACE MOUNT TRANSISTOR**

### Features

- V<sub>CEO</sub> = 40V
- I<sub>c</sub> = 200mA
- Epitaxial Planar Die Construction
- Ideally Suited for Automated Assembly Processes
- Lead, Halogen and Antimony Free, RoHS Compliant (Note 1)
- "Green" Device (Note 2)
- Ultra Small Package

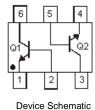
#### **Mechanical Data**

- Case: SOT-963
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.0027 grams (approximate)

SOT-963



Top View



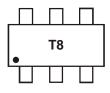
# **Ordering Information**

Device	Packaging	Shipping
DST3904DJ-7	SOT-963	10,000/Tape & Reel

Notes: 1. No purposefully added lead. Halogen and Antimony Free.

2. Diodes Inc's "Green" Policy can be found on our website at http://www.diodes.com

#### **Marking Information**



T8 = Product Type Marking Code



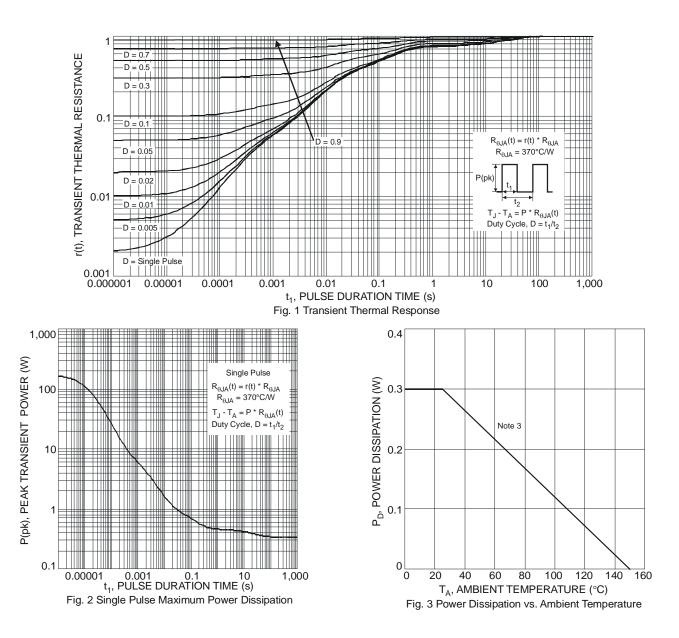
# Maximum Ratings @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	60	V
Collector-Emitter Voltage	V <sub>CEO</sub>	40	V
Emitter-Base Voltage	V <sub>EBO</sub>	6.0	V
Collector Current - Continuous (Note 3)	Ιc	200	mA

### **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 3)	PD	300	mW
Thermal Resistance, Junction to Ambient (Note 3)	$R_{ ext{ heta}JA}$	417	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

Notes: 3. Device mounted on FR-4 PCB with minimum recommended pad layout.

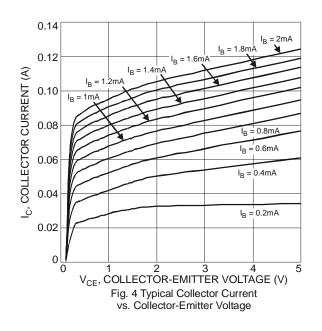


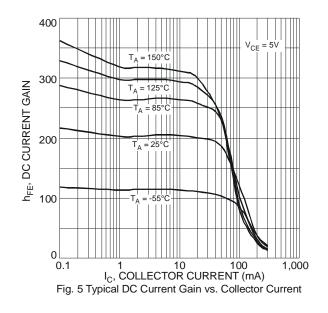


# **Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition	
OFF CHARACTERISTICS					• • • • • •	
Collector-Base Breakdown Voltage	V <sub>(BR)CBO</sub>	60	_	V	$I_{\rm C} = 10 \mu A, I_{\rm E} = 0$	
Collector-Emitter Breakdown Voltage (Note 4)	V <sub>(BR)CEO</sub>	40	—	V	$I_{\rm C} = 1.0 {\rm mA}, I_{\rm B} = 0$	
Emitter-Base Breakdown Voltage	V <sub>(BR)EBO</sub>	6.0	_	V	$I_{E} = 10 \mu A, I_{C} = 0$	
Collector Cutoff Current	I <sub>CEX</sub>	_	50	nA	$V_{CE} = 30V, V_{EB(OFF)} = 3.0V$	
Base Cutoff Current	I <sub>BL</sub>	_	50	nA	$V_{CE} = 30V, V_{EB(OFF)} = 3.0V$	
ON CHARACTERISTICS (Note 4)						
DC Current Gain	h <sub>FE</sub>	40 70 100 60 30	 300 		$ \begin{array}{l} I_{C} = \ 100 \mu A, \ V_{CE} = \ 1.0 V \\ I_{C} = \ 1.0 m A, \ V_{CE} = \ 1.0 V \\ I_{C} = \ 10 m A, \ V_{CE} = \ 1.0 V \\ I_{C} = \ 50 m A, \ V_{CE} = \ 1.0 V \\ I_{C} = \ 100 m A, \ V_{CE} = \ 1.0 V \\ \end{array} $	
Collector-Emitter Saturation Voltage	V <sub>CE(SAT)</sub>		0.20 0.30	V	$I_{C} = 10$ mA, $I_{B} = 1.0$ mA $I_{C} = 50$ mA, $I_{B} = 5.0$ mA	
Base-Emitter Saturation Voltage	V <sub>BE(SAT)</sub>	0.65	0.85 0.95	V	$I_{C} = 10$ mA, $I_{B} = 1.0$ mA $I_{C} = 50$ mA, $I_{B} = 5.0$ mA	
SMALL SIGNAL CHARACTERISTICS						
Output Capacitance	C <sub>obo</sub>	_	4.0	pF	$V_{CB} = 5.0V, f = 1.0MHz, I_E = 0$	
Input Capacitance	C <sub>ibo</sub>	_	8.5	pF	$V_{EB} = 0.5V$ , f = 1.0MHz, I <sub>C</sub> = 0	
nput Impedance	h <sub>ie</sub>	1.0	10	kΩ	V <sub>CE</sub> = 10V, I <sub>C</sub> = 1.0mA,	
Voltage Feedback Ratio	h <sub>re</sub>	0.5	8.0	x 10 <sup>-4</sup>		
Small Signal Current Gain	h <sub>fe</sub>	100	400	—	f = 1.0 kHz	
Output Admittance	h <sub>oe</sub>	1.0	40	μS	]	
Current Gain-Bandwidth Product	fT	300	—	MHz	$V_{CE} = 20V, I_{C} = 10mA,$ f = 100MHz	
SWITCHING CHARACTERISTICS						
Delay Time	t <sub>d</sub>		35	ns	$V_{CC} = 3.0V, I_{C} = 10mA,$	
Rise Time	tr	_	35	ns	$V_{BE(off)} = -0.5V, I_{B1} = 1.0mA$	
Storage Time	ts	_	200	ns	$V_{CC} = 3.0V, I_{C} = 10mA,$	
Fall Time	t <sub>f</sub>	_	50	ns	$I_{B1} = I_{B2} = 1.0 \text{mA}$	

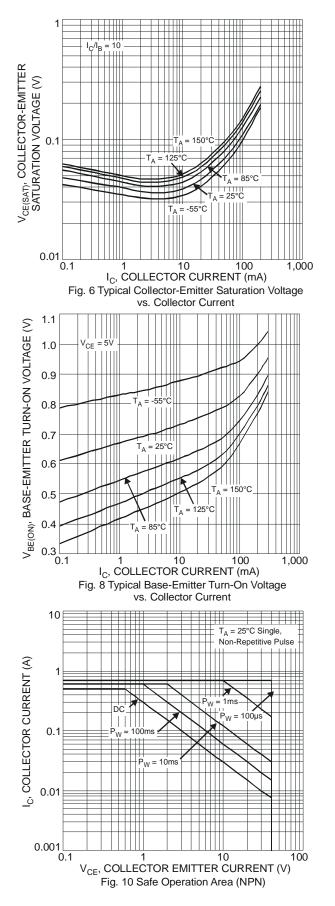
Notes: 4. Measured under pulsed conditions. Pulse width =  $300\mu$ s. Duty cycle  $\leq 2\%$ 

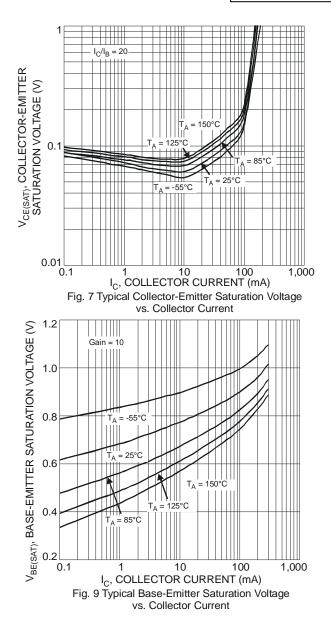






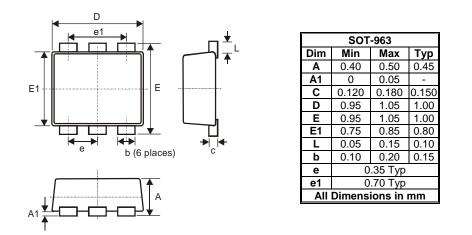
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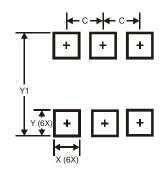




# Package Outline Dimensions



# Suggest Pad Layout



Dimensions	Value (in mm)
С	0.350
Х	0.200
Y	0.200
Y1	1.100



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